# USE AND APPLICATION OF THE NETZSCH DMA



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#### Introduction

- The machine used was the Netzsch DMA Eplexor.
- The film used within the tests was Kapton film.
- The main focus was to use the DMA as a Universal tester, it was used to compare break strength versus
  - Strain rate
  - Temperature (high)

#### Break Strength vs. Strain Rate

- This test is one of the most important things that a Universal Tester can do, the ability to do this is very important for the success of the DMA.
- The success of this test affirmed the viability of the DMA.
  - With the DMA being successful other tests could be done both using high temperatures and sub ambient temperatures, the latter tests use much less liquid nitrogen per test compared to an Instron.

## Break Strength vs. Strain Rate Graph

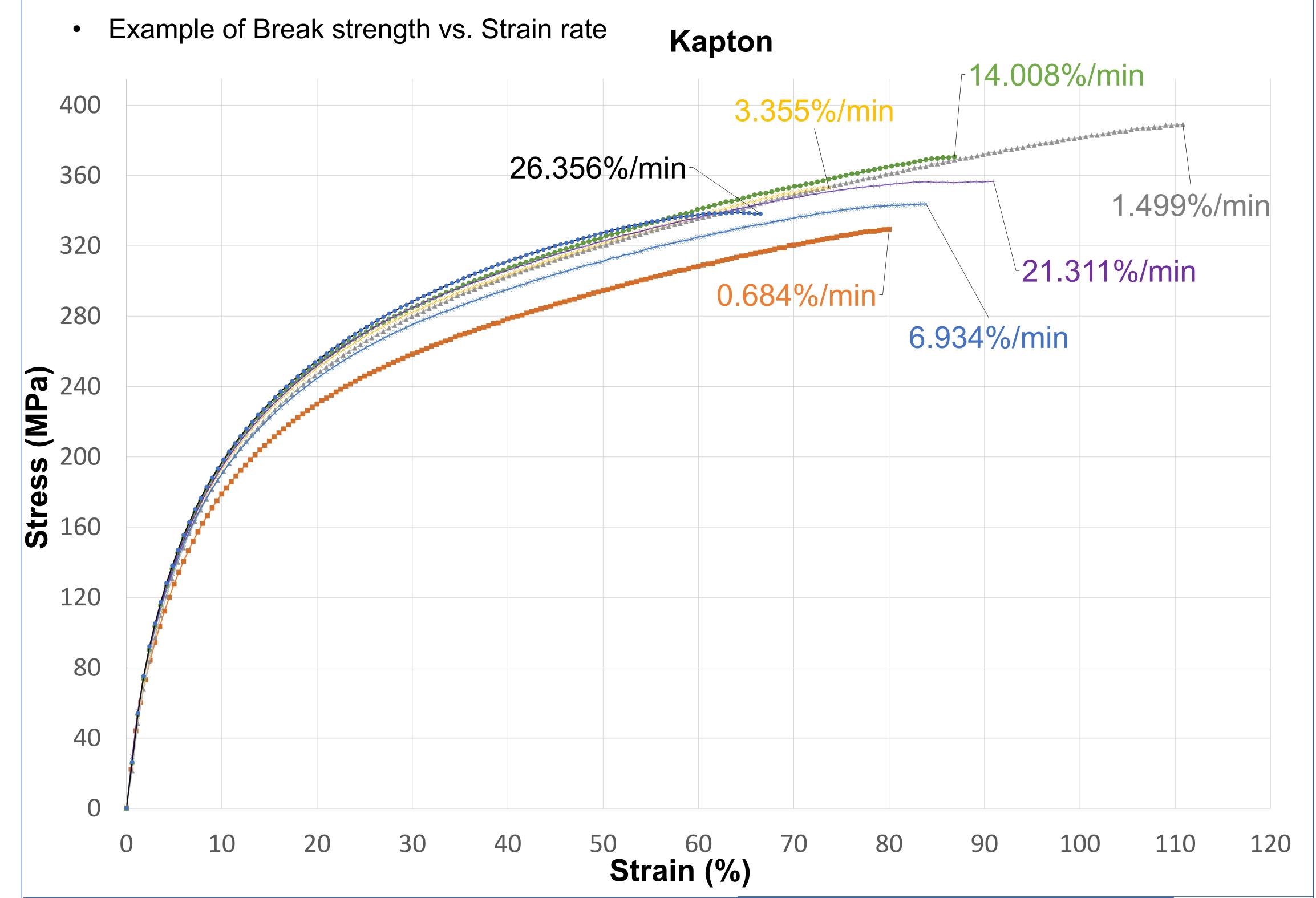


Table Containing Strain, Stress, and Temperature

Temp C	Strain rate %/min	Stress (MPa)
Ambient (≈ 25)	(various, values from graph)	354.538
75	6.184	184.857
100	6.865	162.673
200	14.091	134.103
200	0.685	213.873
Dupont's figures		
22.778	Unknown	231
200	Unknown	139

#### **Possible Future Studies**

- One of the possible things to do with the DMA is to do break strength vs. sub ambient temperatures, this is mentioned in section 1 but no data is included from this, there were test with this idea but the 500 N motor must be installed for best results (the 150 N is the one currently being used for these tests, it was often maxed out).
- The other possible thing is break strength vs. relative humidity, this is not something that has previously been tested unlike sub ambient temperatures.
- In the future other materials should be used and tested on to ensure it truly is a good mechanical tester for a wide range of films, the only confirmed film is Kapton.
- The only type of experiment done was a pull to break for the data received, in the future other tests including compression can be done as well.

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